# 產品規格書

# **Market Requirement Document**

	CUSTO	OMER:							
PRODUCT:		声表面谐振器							
MODEL:		R154M							
PARAMETER:		F11-DIP							
DATE:					•				
		<u>-</u>							
承認後請寄回一份									
<b>承祕仮萌句凹一</b> 勿 PLEASE RETURN ONE COPY TO US SO THAT WE GET YOUR APPROVAL									
1									
承認結果	客戶簽名	客戶承認章		日期	備注				
CONCLUSION	SIGNATURE	STAMP		DATE	REMARK				
合格									
ACCEPT									
不合格									
REJECT									
制表: 钟先生		·	审核:						
		·	+1/1/2:		(公章)				
<i>尊敬的客户:请您抽出</i>	出一点时间,在 <i>7-10个</i> 二	工作日内将承认书回签,	若未回签。	. 以视默认. 谢谢:					

# 1. SCOPE

This specification is applied to a SAW resonator designed for the stabilization of transmitters such as garage door openers and security transmitters.

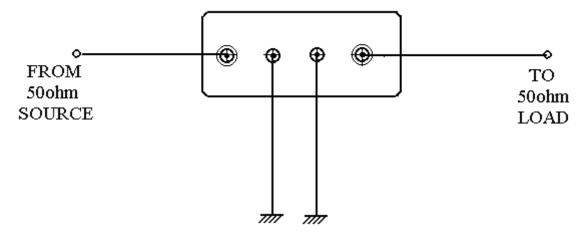
# 2. ELECTRICAL SPECIFICATION

DC Voltage VDC	30V		
AC Voltage Vpp	10V50Hz/60Hz		
Operation temperature	-40°C to +85°C		
Storage temperature	-45°C to +85°C		
RF Power Dissipation	0dBm		

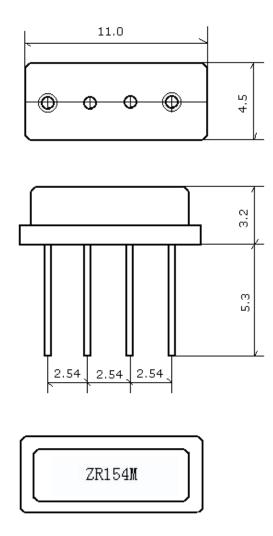
# 2.2 Electronic Characteristics

Item		Unites	Minimum	Typical	Maximum
Center Frequency		MHz	153.925	154.000	154.075
Insertion Loss		dB		2.2	2.5
Quality Factor Unload Q			14000	14500	
50 Ω Loaded Q			3000	4000	
Temperature T	urnover Temperature	$^{\circ}\mathbb{C}$	10	25	40
Stability F	req.temp.Coefficient	ppm/°C2		0.037	
Frequency Aging		ppm/yr		<±10	
DC. Insulation Resistance		МΩ	1.0		
RF Equivalent RLC Model	Motional Resistance R1	Ω		28	30
	Motional Inductance L1	μН		532.63	
	Motional Capacitance C1	fF		2.0053	
Transducer Static Capacitance		pF		2.6	

# 3. TEST CIRCUIT



# 4. DIMENSION



# 5. ENVIRONMENTAL CHARACTERISTICS

#### 5-1 High temperature exposure

Subject the device to +85°C for 16 hours. Then release the resonator into the room conditions for 24 hours prior to the measurement. It shall fulfill the specifications in 2.2.

# 5-2 Low temperature exposure

Subject the device to  $-40^{\circ}$ C for 16 hours. Then release the device into the room conditions for 24 hours prior to the measurement. It shall fulfill the specifications in 2.2.

# 5-3 Temperature cycling

Subject the device to a low temperature of -40°C for 30 minutes. Following by a high temperature of +85°C for 30 Minutes. Then release the device into the room conditions for 24 hours prior to the measurement. It shall meet the specifications in 2.2.

#### 5-4 Resistance to solder heat

Dip the device terminals no closer than 1.5mm into the solder bath at  $260^{\circ}$ C  $\pm 10^{\circ}$ C for  $10\pm 1$  sec. Then release the device into the room conditions for 4 hours. The device shall meet the specifications in 2.2.

#### 5-5 Solderability

Subject the device terminals into the solder bath at  $245^{\circ}$ C  $\pm 5^{\circ}$ C for 5s, More than 95% area of the terminals must be covered with new solder. It shall meet the specifications in 2.2.

#### 5-6 Mechanical shock

Drop the device randomly onto the concrete floor from the height of 1m 3 times. the device shall fulfill the specifications in 2.2.

#### 5-7 Vibration

Subject the device to the vibration for 1 hour each in x, y and z axes with the amplitude of 1.5 mm at 10 to 55 Hz. The device shall fulfill the specifications in 2.2.

# 6. REMARK

#### 6.1 Static voltage

Static voltage between signal load & ground may cause deterioration &destruction of the component. Please avoid static voltage.

# 6.2 Ultrasonic cleaning

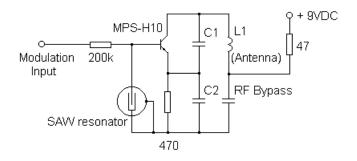
Ultrasonic vibration may cause deterioration & destruction of the component. Please avoid ultrasonic cleaning

#### 6.3 Soldering

Only leads of component may be soldered. Please avoid soldering another part of component.

# 7.TYPCIAL APPLICATION CIRCUITS

# Typical low-power Transmitter Application



# Typical Local Oscillator Application

